FAIRCHILD

SEMICONDUCTOR®

FDP8441_F085

N-Channel PowerTrench[®] MOSFET 40V, 80A, 2.7m Ω

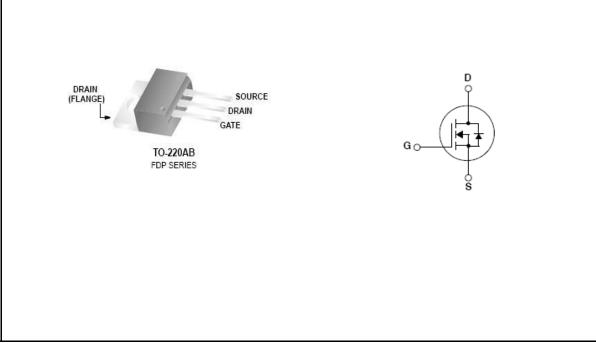
Features

- Typ $r_{DS(on)} = 2.1m\Omega$ at $V_{GS} = 10V$, $I_D = 80A$
- Typ Q_{g(10)} = 215nC at V_{GS} = 10V
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

AD OF REE E SHALL MENTATION

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alternator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems



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FDP8441_F085 N-Channel PowerTrench[®] MOSFET

May 2010

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Index of our of control only ofIndex of our of our of only of the second o	/ _{DS}	Drain to Sou	rce Voltage				40)	V
DContinuous ($T_{amb} = 25^{\circ}C$, $V_{GS} = 10V$, with $R_{0JA} = 62^{\circ}C/W$)23APulsedSee Figure 4EASSingle Pulse Avalanche Energy(Note 1)947mJDPower dissipation300WDerate above $25^{\circ}C$ 2 $W/^{\circ}C$ T_J, T_{STG}Operating and Storage Temperature-55 to 175 $^{\circ}C$ CharacteristicsR _{0JC} Thermal Resistance Junction to Case0.5 $^{\circ}C/W$ R_{0JA} Thermal Resistance Junction to Ambient(Note 2)62 $^{\circ}C/W$	/ _{GS}	Gate to Sour	ce Voltage				±2	0	V
PulsedSee Figure 4EASSingle Pulse Avalanche Energy(Note 1)947mJPower dissipation300WDerate above 25°C2W/°CTJ, TSTGOperating and Storage Temperature-55 to 175°CCharacteristicsReJCThermal Resistance Junction to Case0.5°C/WReJAThermal Resistance Junction to Ambient(Note 2)62°C/W		Drain Curren	t Continuous (T _C < 160°C, V _{GS}	= 10V)		80)	
EAS Single Pulse Avalanche Energy (Note 1) 947 mJ Power dissipation 300 W Derate above 25°C 2 W/°C FJ, T _{STG} Operating and Storage Temperature -55 to 175 °C Thermal Characteristics R _{0JC} Thermal Resistance Junction to Case 0.5 °C/W R _{0JA} Thermal Resistance Junction to Ambient (Note 2) 62 °C/W	D	Continuous ($T_{amb} = 25^{\circ}C,$	V _{GS} = 10V, with F	$R_{\theta JA} = 62^{\circ}C/W$		23		Α
Power dissipation 300 W Derate above 25°C 2 W/°C T _J , T _{STG} Operating and Storage Temperature -55 to 175 °C Thermal Characteristics R _{0JC} Thermal Resistance Junction to Case 0.5 °C/W R _{0JA} Thermal Resistance Junction to Ambient (Note 2) 62 °C/W		Pulsed					See Fig	gure 4	
Derate above 25°C 2 W/°C J, T _{STG} Operating and Storage Temperature -55 to 175 °C Thermal Characteristics R _{0JC} Thermal Resistance Junction to Case 0.5 °C/W R _{0JA} Thermal Resistance Junction to Ambient (Note 2) 62 °C/W	AS	Single Pulse	Avalanche En	ergy		(Note 1)	94	7	mJ
Derate above 25°C W/°C T _J , T _{STG} Operating and Storage Temperature -55 to 175 °C Thermal Characteristics R _{0JC} Thermal Resistance Junction to Case 0.5 °C/W R _{0JA} Thermal Resistance Junction to Ambient (Note 2) 62 °C/W	,	Power dissip	ation				30	0	W
Chermal Characteristics 0.5 °C/W R _{θJA} Thermal Resistance Junction to Case 0.5 °C/W	D	Derate above	e 25°C				2		W/ºC
Thermal Characteristics R _{0JC} Thermal Resistance Junction to Case 0.5 °C/W R _{0JA} Thermal Resistance Junction to Ambient (Note 2) 62 °C/W									
				nperature			-55 to	175	°C
	R _{θJC} R _{θJA}	Characte Thermal Res Thermal Res Marking	eristics istance Junctio	on to Case	mation Reel Size		0.	5	°C/W

Thermal Characteristics

R_{\thetaJC}	Thermal Resistance Junction to Case		0.5	°C/W
R_{\thetaJA}	Thermal Resistance Junction to Ambient	(Note 2)	62	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8441	FDP8441_F085	TO-220AB	Tube	N/A	50 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol Parameter Test Conditions Min Typ Max Units							
	Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Off Characteristics

B _{VDSS}	Drain to Source Breakdown Voltage	$I_{D} = 250 \mu A, V_{C}$	as = 0V	40	-	-	V
1	Zero Gate Voltage Drain Current	$V_{DS} = 32V$		-	-	1	μA
DSS	Zero Gale Vollage Drain Current	$V_{GS} = 0V$	$T_J = 150^{\circ}C$	-	-	250	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

On Characteristics

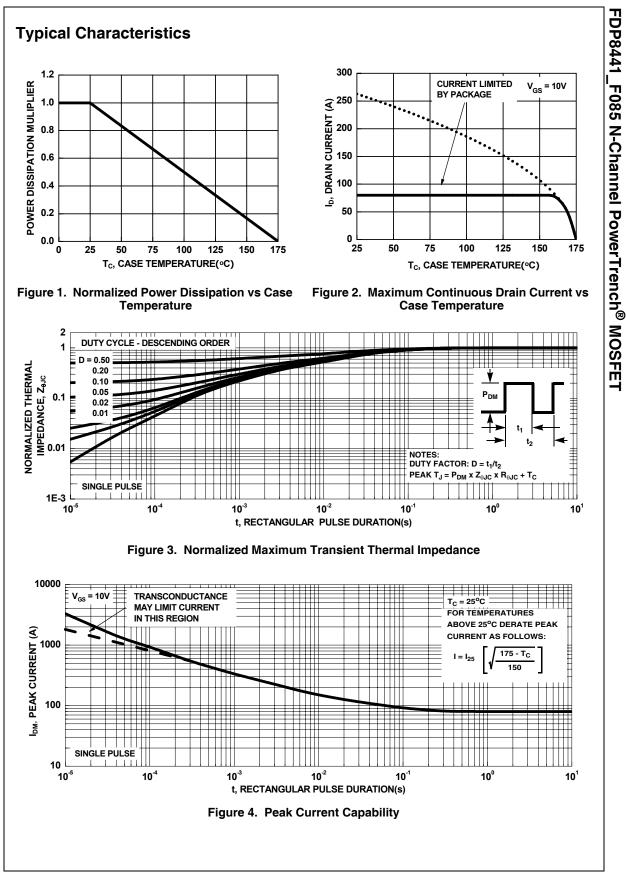
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	2.8	4	V
		$I_{D} = 80A, V_{GS} = 10V$	-	2.1	2.7	
r _{DS(on)}	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V, T_J = 175^{\circ}C$	-	3.6	4.7	mΩ

Dynamic Characteristics

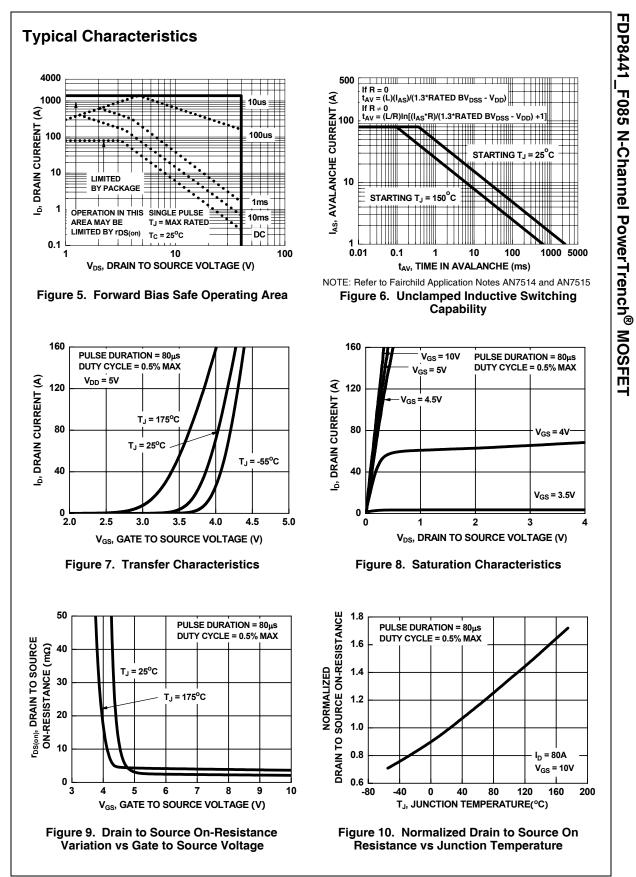
C _{iss}	Input Capacitance		0)/	-	15000	-	pF
C _{oss}	Output Capacitance	— V _{DS} = 25V, V _{GS} — f = 1MHz	= 0V,	-	1250	-	pF
C _{rss}	Reverse Transfer Capacitance			-	685	-	pF
R _G	Gate Resistance	V _{GS} = 0.5V, f = 1	MHz	-	1.1	-	Ω
Q _{g(TOT)}	Total Gate Charge at 10V	V _{GS} = 0 to 10V		-	215	280	nC
Q _{g(TH)}	Threshold Gate Charge	$V_{GS} = 0$ to 2V	V _{DD} = 20V	-	29	38	nC
Q _{gs}	Gate to Source Gate Charge		I _D = 35A	-	60	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		l _g = 1mA	-	32	-	nC
Q _{gd}	Gate to Drain "Miller" Charge			-	49	-	nC

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switching	g Characteristics					
t _(on)	Turn-On Time		-	-	77	ns
t _{d(on)}	Turn-On Delay Time		-	23	-	ns
t _r	Turn-On Rise Time	V _{DD} = 20V, I _D = 35A	-	24	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 1.5\Omega$	-	75	-	ns
•α(oπ)						
	Turn-Off Fall Time		-	17.9	-	ns
f	Turn-Off Time		-	17.9 -	- 147	ns ns
t _í t _{off} Drain-So	Turn-Off Time urce Diode Characteristics	I _{SD} = 35A		-		_
t _f t	Turn-Off Time	I _{SD} = 35A I _{SD} = 15A	-	-	147	ns
t _í t _{off} Drain-So	Turn-Off Time urce Diode Characteristics		-	- 0.8	147 1.25	ns V

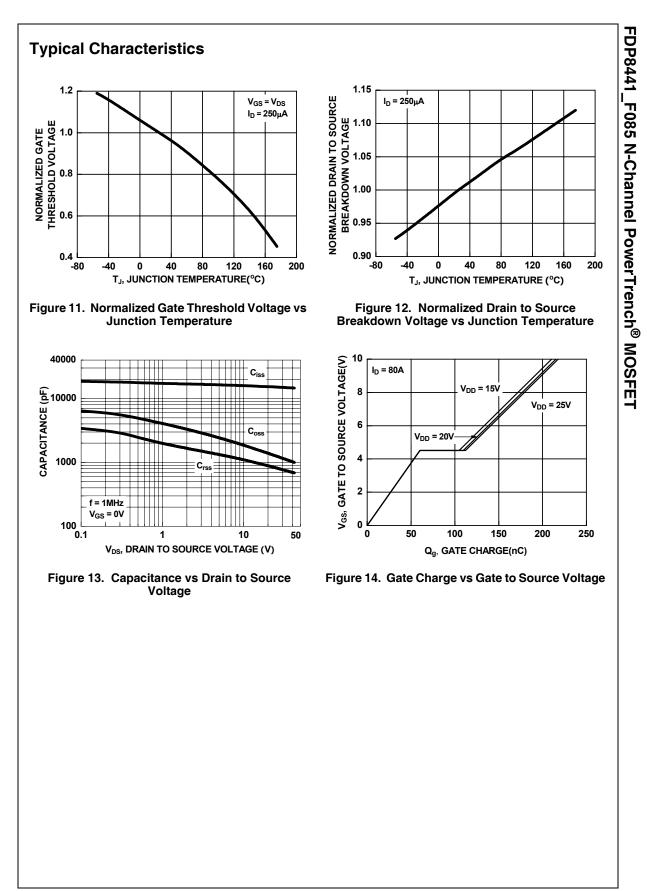
V	Source to Drain Diode Voltage	I _{SD} = 35A	-	0.8	1.25	V
V _{SD}	Source to Drain Didde Voltage	I _{SD} = 15A	-	0.8	1.0	V
t _{rr}	Reverse Recovery Time	I _F = 35A, di/dt = 100A/μs	-	52	68	ns
Q _{rr}	Reverse Recovery Charge	I _F = 35A, di/dt = 100A/μs	-	76	99	nC



FDP8441_F085 Rev.A1



FDP8441_F085 Rev.A1



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Sync-Lock™

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